

Subst. Form PTO-1449		Docket Number (Optional) 56247-235 (CSLL-662CP)	Application Number 10/642,315				
<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  <i>(Use several sheets if necessary)</i>		Applicant Sawyer, et al.					
		Filing Date 8/15/2003	Group Art Unit				
U. S. Patent Documents							
EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		6,077,721	06-2000	Fukuda et al.			
		6,277,666	08-2001	Hays et al.			
		6,431,714	08-2002	Sawada et al.			
		6,423,563	07-2002	Fukads			
		4,079,508	03-1979	Nunn			
		6,252,294	06-2002	Hattori			
		6,171,881	01-2002	Fujii			
		5,488,012	01-1996	McCarthy			
		5,760,443	06-1998	McCarthy			
		3,922,705	11-1975	Yerman			
		6,105,427	08-2000	Stewart, et al.			
		6,458,615	10-2002	Fedder, et al.			
		5,501,893	03-1996	Laermer, et al.			
FOREIGN PATENT DOCUMENTS							
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
		Copy of International Search Report PCT/US02/00015					
	C1	Moore DF, "Silicon-on insulator material for sensors and accelerometers" Silicon Fabricated Inertial instruments, 9/1-9/5 (December 1996)					
	C2	Syms RRA et al., "Surface tension powered self-assembly of 3D MOEMS devices using DRIE of bonded silicon-on-insulator wafers." IEEE Seminar on Demonstrated Micromachining Technologies for Industry, 1/1-1/6 (March 2000)					
	C3	Yamamoto T et al. "Capacitive accelerometer with high aspect ratio single crystalline silicon microstructure using SOI structure with polysilicon-based interconnect technique." Micro Electro Mechanical Systems, 515-519 (January 2000)					
	C4	Martin A. Schmidt, "Wafer-to-Wafer Bonding for Microstructure Formation", Proceedings of the IEEE, Vol. 86, No. 8, August 1998.					
EXAMINER 				DATE CONSIDERED 1/23/05			
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy with next communication to applicant.							